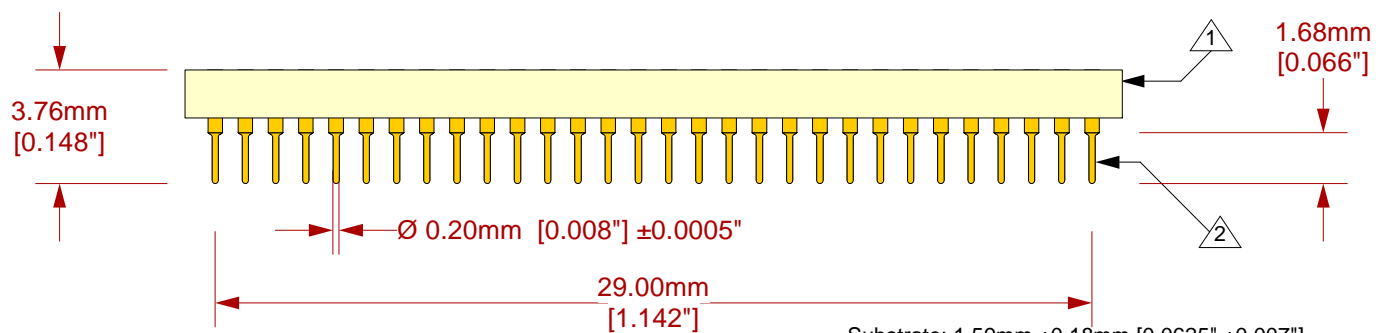


Side View




① Substrate: 1.59mm $\pm 0.18\text{mm [0.0625"} \pm 0.007"$ FR4/G10 or equivalent high temp material.

② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 $\mu\text{m [10}\mu\text{"}$ Au over 1.27 $\mu\text{m [50}\mu\text{"}$ Ni (min.).

Description: Giga-snaP BGA SMT Land Socket

516 position BGA surface mount land pattern to terminal pins (1.0mm [0.039"] centers, 30x30 array)

Tolerances: diameters $\pm 0.03\text{mm [}\pm 0.001\text{"}$, PCB perimeters $\pm 0.13\text{mm [}\pm 0.005\text{"}$, PCB thicknesses $\pm 0.18\text{mm [}\pm 0.007\text{"}$, pitches (from true position) $\pm 0.08\text{mm [}\pm 0.003\text{"}$, all other tolerances $\pm 0.13\text{mm [}\pm 0.005\text{"}$ unless stated otherwise. Materials and specifications are subject to change without notice.

| | | | | |
|---|---|-------------------------|---------------|--------|
|  | LS-BGA516B-41 Drawing © 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com | Status: Released | Scale: 4:1 | Rev: A |
| | | Drawing: M.A.Fedde | Date: 12/9/05 | |
| | | File: LS-BGA516B-41 Dwg | Modified: | |